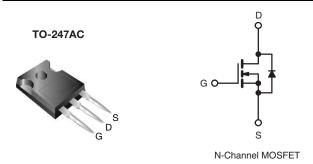


Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	400				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 0.30				
Q _g (Max.) (nC)	76				
Q _{gs} (nC)	20				
Q _{gd} (nC)	37				
Configuration	Single				



FEATURES

- Ultra Low Gate Charge
- Reduced Gate Drive Requirement
- Enhanced 30V V_{GS} Rating
- Reduced Ciss, Coss, Crss
- Isolated Central Mounting Hole
- Dynamic dV/dt Rated
- Repetitive Avalanche Rated
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

This new series of low charge Power MOSFETs achieve significantly lower gate charge over conventional MOSFETs. Utilizing advanced MOSFETs technology the device improvements allow for reduced gate drive requirements, faster switching speeds and increased total system savings. These device improvements combined with the proven ruggedness and reliability of MOSFETs offer the designer a new standard in power transistors for switching applications.

The TO-247AC package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220AB devices. The TO-247AC is similar but superior to the earlier TO-218 package because of its isolated mounting hole.

ORDERING INFORMATION		
Package	TO-247AC	
Load (Dh) froe	IRFP350LCPbF	
Lead (Pb)-free	SiHFP350LC-E3	
SnPb	IRFP350LC	
SIFD	SiHFP350LC	

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	400	V		
Gate-Source Voltage		V_{GS}	± 30	V	
Continuous Drain Current	V_{GS} at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$,	16	А	
Continuous Drain Current	$T_C = 100 ^{\circ}C$	ID	9.9		
Pulsed Drain Current ^a	I _{DM}	64			
Linear Derating Factor		1.5	W/°C		
Single Pulse Avalanche Energy ^b	E _{AS}	390	mJ		
Repetitive Avalanche Current ^a	I _{AR}	16	Α		
Repetitive Avalanche Energy ^a	E _{AR}	19	mJ		
Maximum Power Dissipation	P_{D}	190	W		
Peak Diode Recovery dV/dtc	dV/dt	4.0	V/ns		
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to + 150	°C		
Soldering Recommendations (Peak Temperature)		300 ^d			
M. P. T. C.	6-32 or M3 screw		10	lbf ⋅ in	
Mounting Torque	0-32 OF IVIS SCIEW		1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. $V_{DD} = 25 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 2.7 \,^{\circ}\text{mH}$, $R_g = 25 \,^{\circ}\Omega$, $I_{AS} = 16 \,^{\circ}\text{A}$ (see fig. 12).
- c. $I_{SD} \le 16$ A, $dI/dt \le 200$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRFP350LC, SiHFP350LC

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THERMAL RESISTANCE RATINGS					
PARAMETER	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	40		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.24	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.65		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0	Ο V, I _D = 250 μA	400	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA	-	0.49	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V$	/ _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	Vo	_{SS} = ± 20 V	=	-	± 100	nA
Zero Gate Voltage Drain Current	l	$V_{DS} = 4$	100 V, V _{GS} = 0 V	=	-	25	μА
Zero Gate voltage Drain Current	I _{DSS}	V _{DS} = 320 V, V	V _{GS} = 0 V, T _J = 125 °C	=	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 9.6 A^b$	-	-	0.30	Ω
Forward Transconductance	9 _{fs}	$V_{DS} = 5$	50 V, I _D = 9.6 A ^b	8.1	-	-	S
Dynamic		·					
Input Capacitance	C _{iss}	٧	V _{GS} = 0 V,		2200	-	
Output Capacitance	C _{oss}	v	V _{DS} = 25 V,		390	-	pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0	f = 1.0 MHz, see fig. 5		31	-	
Total Gate Charge	Q_g			-	-	76	nC
Gate-Source Charge	Q_{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 16 \text{ A}, V_{DS} = 320 \text{ V}$ see fig. 6 and 13 ^b		-	20	
Gate-Drain Charge	Q_{gd}		see lig. o and 10	-	-	37	
Turn-On Delay Time	t _{d(on)}	·		-	14	-	
Rise Time	t _r	V _{DD} = 200 V, I _D = 16 A,		-	54	-	
Turn-Off Delay Time	t _{d(off)}	$R_0 = 6.2 \Omega$. R	$R_{\rm q} = 6.2 \ \Omega, \ R_{\rm D} = 12 \ \Omega, \ {\rm see \ fig. \ 10^b}$		33	-	ns
Fall Time	t _f			-	35	-	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbo	MOSFET symbol showing the		-	16	A
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	-	64	^
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 16 A, V _{GS} = 0 V ^b		-	-	1.6	٧
Body Diode Reverse Recovery Time	t _{rr}	- T _J = 25 °C, I _F = 16 A, dI/dt = 100 A/μs ^b		1	440	660	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	4.1	6.2	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D				1-2)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

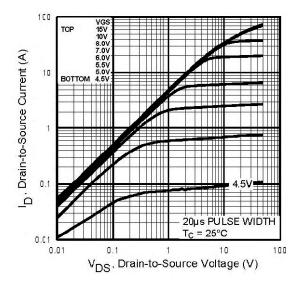


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

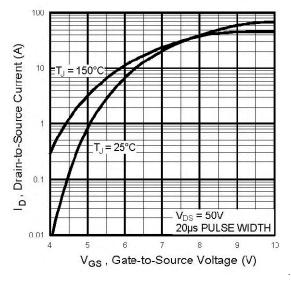


Fig. 3 - Typical Transfer Characteristics

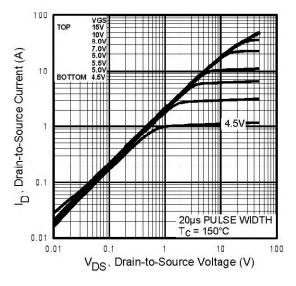


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

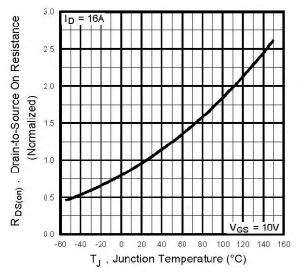


Fig. 4 - Normalized On-Resistance vs. Temperature

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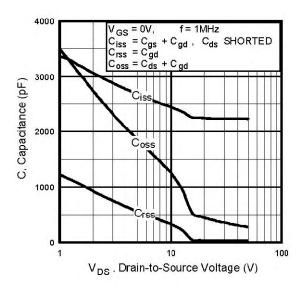


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

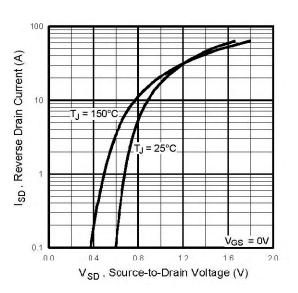


Fig. 7 - Typical Source-Drain Diode Forward Voltage

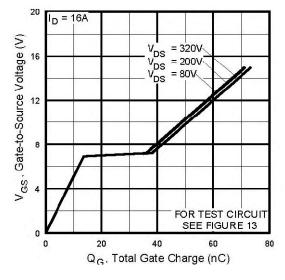


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

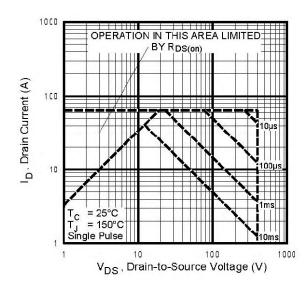


Fig. 8 - Maximum Safe Operating Area



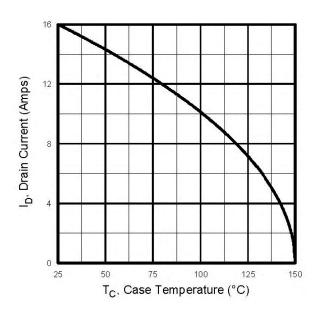


Fig. 9 - Maximum Drain Current vs. Case Temperature

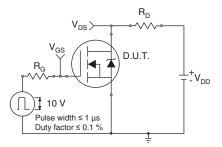


Fig. 10a - Switching Time Test Circuit

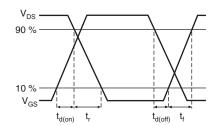


Fig. 10b - Switching Time Waveforms

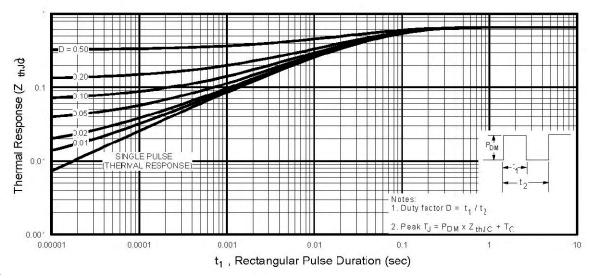


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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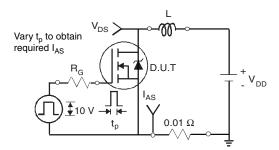


Fig. 12a - Unclamped Inductive Test Circuit

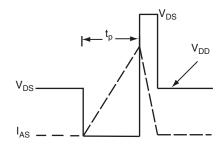


Fig. 12b - Unclamped Inductive Waveforms

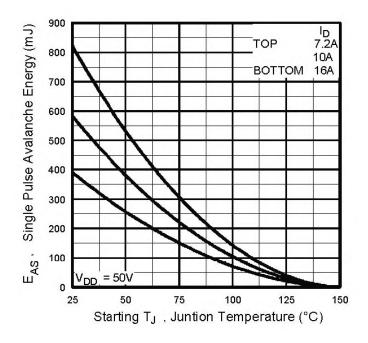


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

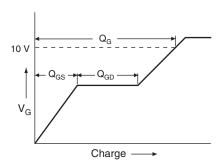


Fig. 13a - Basic Gate Charge Waveform

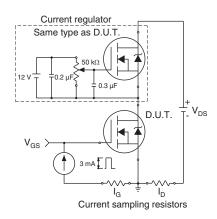
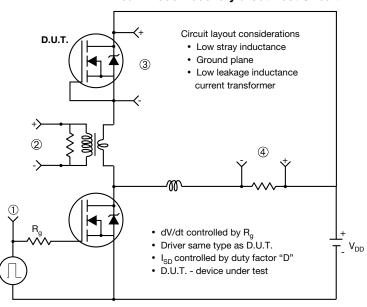


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



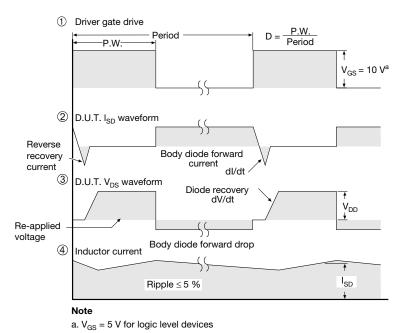
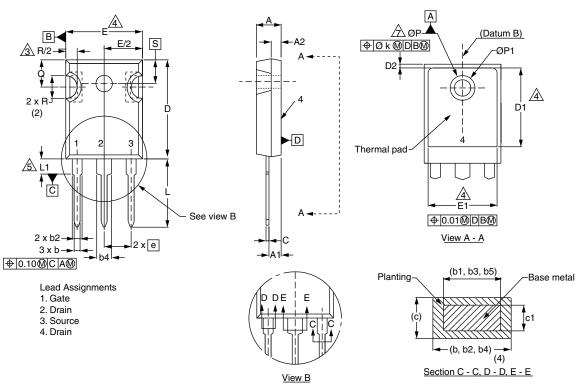


Fig. 14 - For N-Channel

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TO-247AC (High Voltage)



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	ı	0.540	ı
е	5.46	BSC	0.215 BSC	
Øk	0.2	254	0.010	
L	14.20	16.25	0.559	0.640
L1	3.71	4.29	0.146	0.169
N	7.62 BSC		0.300 BSC	
ØΡ	3.51	3.66	0.138	0.144
Ø P1	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217 BSC	
0.01 800 0.217 800				

ECN: X13-0103-Rev. D, 01-Jul-13

DWG: 5971

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
 5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.





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